**Product data sheet** 

# 1. General description

Silicon Carbide Schottky diode (Bare Die).

## 2. Features and benefits

- · Extremely fast reverse recovery time
- Low figure of merit (Q<sub>r</sub>\*V<sub>F</sub>)
- · Highly stable switching performance
- Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- · RoHS compliant

## 3. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>RRM</sub> *	repetitive peak reverse voltage			-	-	1200	V
I <sub>F(AV)</sub> **	average forward current	$\delta$ = 0.5; square-wave pulse		-	-	15	Α
Static ch	Static characteristics						
V <sub>F</sub> **	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C		-	1.45	1.7	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C		-	1.95	2.3	V
Dynamic characteristics							
<b>Q</b> <sub>r</sub> **	recovered charge	$I_F = 15 \text{ A}$ ; $V_R = 400 \text{ V}$ ; $dI_F/dt = 500 \text{ A}/\mu\text{s}$ ; $T_j = 25 ^{\circ}\text{C}$		-	35	-	nC

# 4. Ordering information

## **Table 2. Ordering information**

Type number	Orderable part number	Name	Description	Version
WB15SC120AL	WB15SC120ALZ	Wafer	Bare die on wafer	Die

# 5. Limiting values

## **Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RRM</sub> *	repetitive peak reverse voltage		-	1200	V
$V_{RWM}^*$	crest working reverse voltage		-	1200	V
$V_R^*$	reverse voltage	DC	-	1200	V
I <sub>F(AV)</sub> **	average forward current	δ = 0.5; square-wave pulse	-	15	А
I <sub>FRM</sub> **	repetitive peak forward current	$\delta$ = 0.5; $t_p$ = 25 μs; square-wave pulse	-	30	А
I <sub>FSM</sub> **	non-repetitive peak forward current	$t_p = 10 \text{ ms; } T_{j(init)} = 25 \text{ °C; sine-wave pulse}$	-	102	А
		$t_p$ = 10 $\mu$ s; $T_{j(init)}$ = 25 °C; square-wave pulse	-	950	А
T <sub>stg</sub> **	storage temperature		-55	175	°C
T <sub>j</sub> **	junction temperature		-	175	°C

## 6. Characteristics

#### **Table 4. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V <sub>F</sub> *	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C	-	1.45	1.7	V
V <sub>F</sub> **	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C	-	1.95	2.3	V
l <sub>R</sub> *	reverse current	V <sub>R</sub> = 1200 V; T <sub>j</sub> = 25 °C	-	5	150	μA
I <sub>R</sub> **	reverse current	V <sub>R</sub> = 1200 V; T <sub>j</sub> = 150 °C	-	80	-	μA
Dynamic	characteristics		,		'	
Q <sub>r</sub> **	recovered charge	$I_F = 15 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s};$ $T_j = 25 ^{\circ}\text{C}$	-	35	-	nC
C <sub>d</sub> **	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C	-	700	-	pF
		f = 1 MHz; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C	-	65	-	pF
		f = 1 MHz; V <sub>R</sub> = 800 V; T <sub>j</sub> = 25 °C	-	48	-	pF

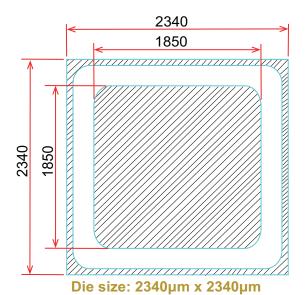
#### Notes:

<sup>(1) \*</sup> mean that parameter are 100% test at  $T_{amb}$  = 25°C

<sup>(2) \*\*</sup> means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet, similar to the assembled devices like WNSC2D151200W.

MECHANICAL PATAMETER			
Chip size	2.34 x 2.34	mm <sup>2</sup>	
Anode pad size	1.85 x 1.85	mm²	
Scribe line width	80	μm	
Area total / active	5.48 / 3.42	mm²	
Thickness	165	μm	
Wafer size	100	mm	
Max possible chips per wafer	1280	pcs	
Passivation	Polyimide		
Front metal	AlCu		
Back metal	Ti Ni Ag		

## **CHIP LAYOUT**



Bond pad size: 1850µm x 1850µm

## 7. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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WeEn Semiconductors WB15SC120AL

Silicon Carbide Schottky diode - Bare Die

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## 8. Contents

1.	General description	1
2.	Features and benefits	1
3.	Quick reference data	1
	Ordering information	
5.	Limiting values	2
6.	Characteristics	3
7.	Legal information	5
	Contents	

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